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United States Patent [19]

Nakao et al.

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[45] Date of Patent: **** May 19, 1992**

[54] **HEAT INSULATING CYLINDER FOR THERMAL TREATMENT OF SEMICONDUCTOR WAFERS**

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[73] Assignee: **Tel Sagami Limited**, Kanagawa, Japan

[*] Notice: The portion of the term of this patent subsequent to May 19, 2006 has been disclaimed.

[**] Term: **14 Years**

[21] Appl. No.: **301,995**

[22] Filed: **Jan. 25, 1989**

[30] **Foreign Application Priority Data**

Jul. 25, 1988 [JP] Japan 63-29836

[52] U.S. Cl. **D15/144.1**

[58] Field of Search D15/144.1; 219/390, 219/411; 432/6, 33, 239, 241, 253, 258, 260, 261

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[57] **CLAIM**

The ornamental design for a heat insulating cylinder for thermal treatment of semiconductor wafers, as shown and described.

DESCRIPTION

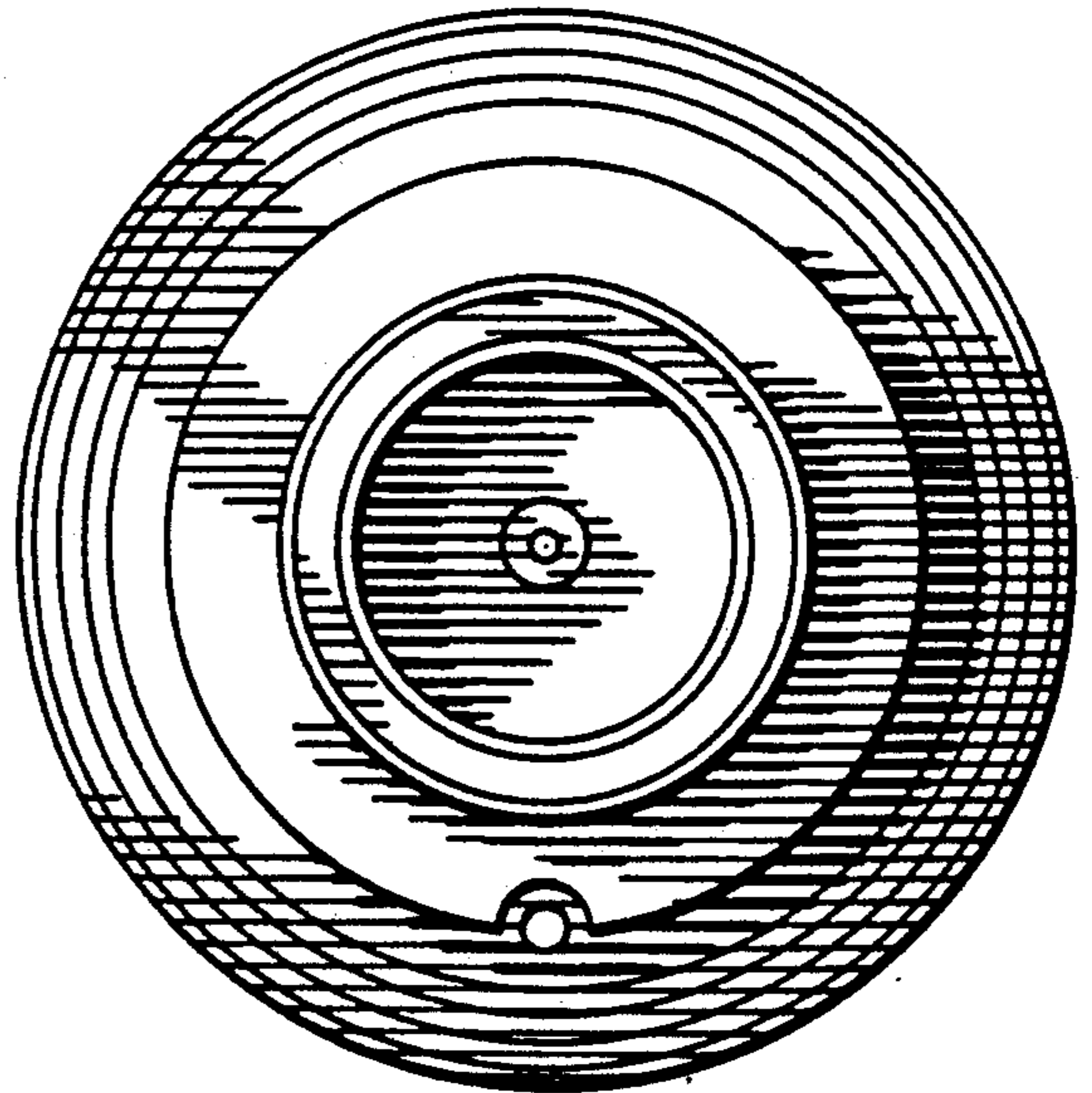
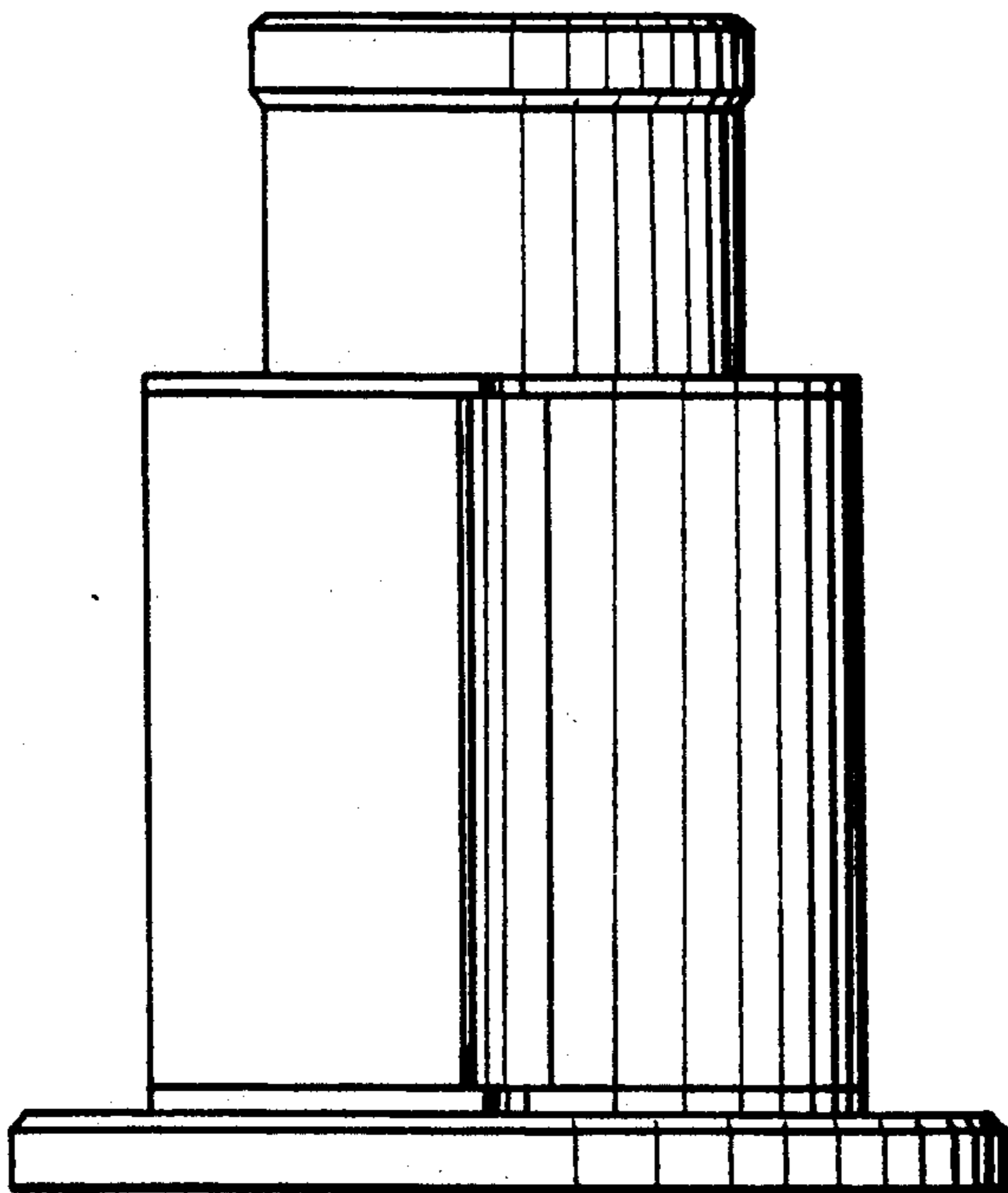
FIG. 1 is a front elevational view of a heat insulating cylinder for thermal treatment of semiconductor wafers showing our new design;

FIG. 2 is a right side elevational view, the left side elevational view being a mirror image;

FIG. 3 is a top plan view;

FIG. 4 is a bottom plan view; and,

FIG. 5 is a rear elevational view thereof.



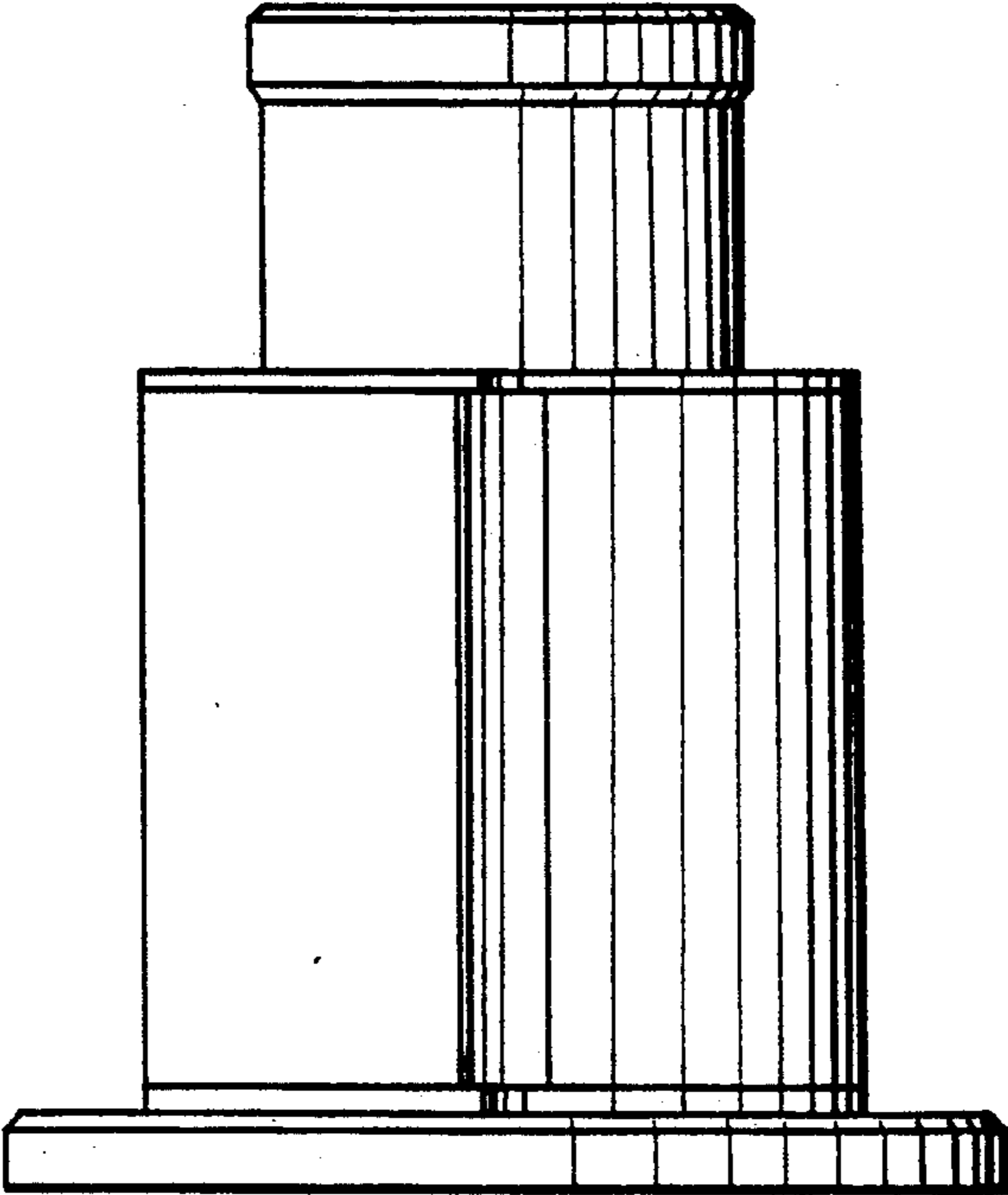


FIG. 1

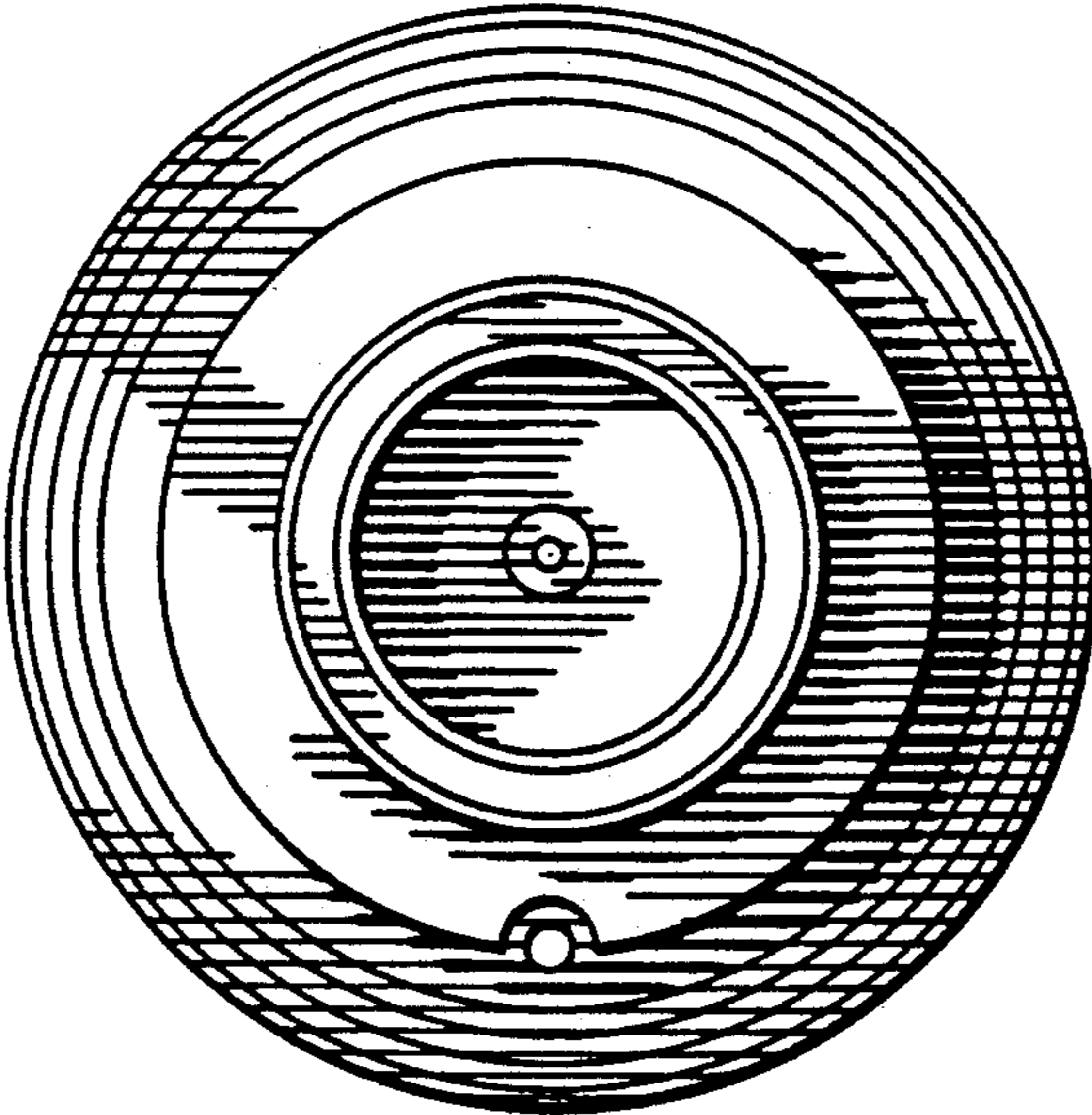


FIG. 3

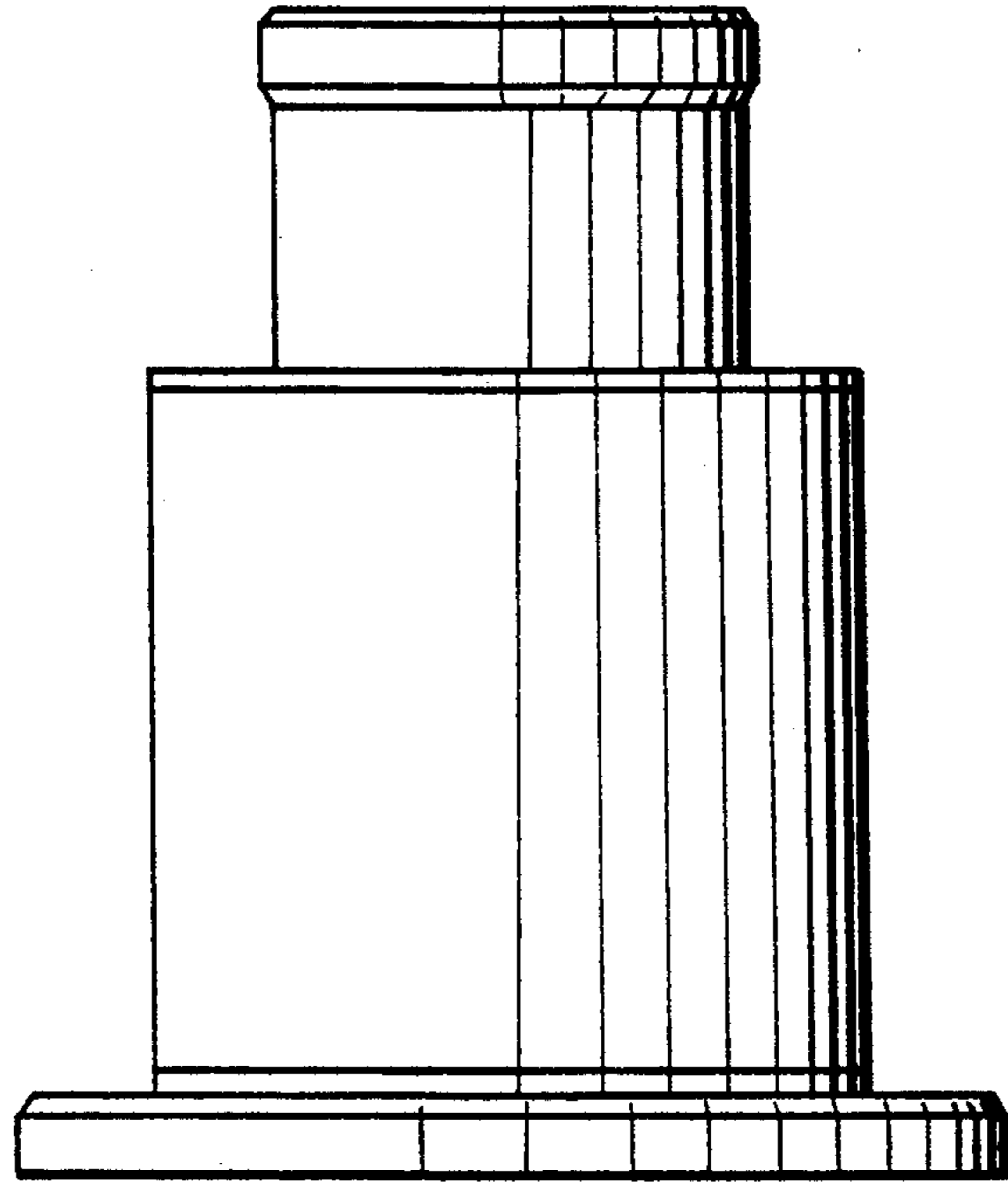


FIG. 2

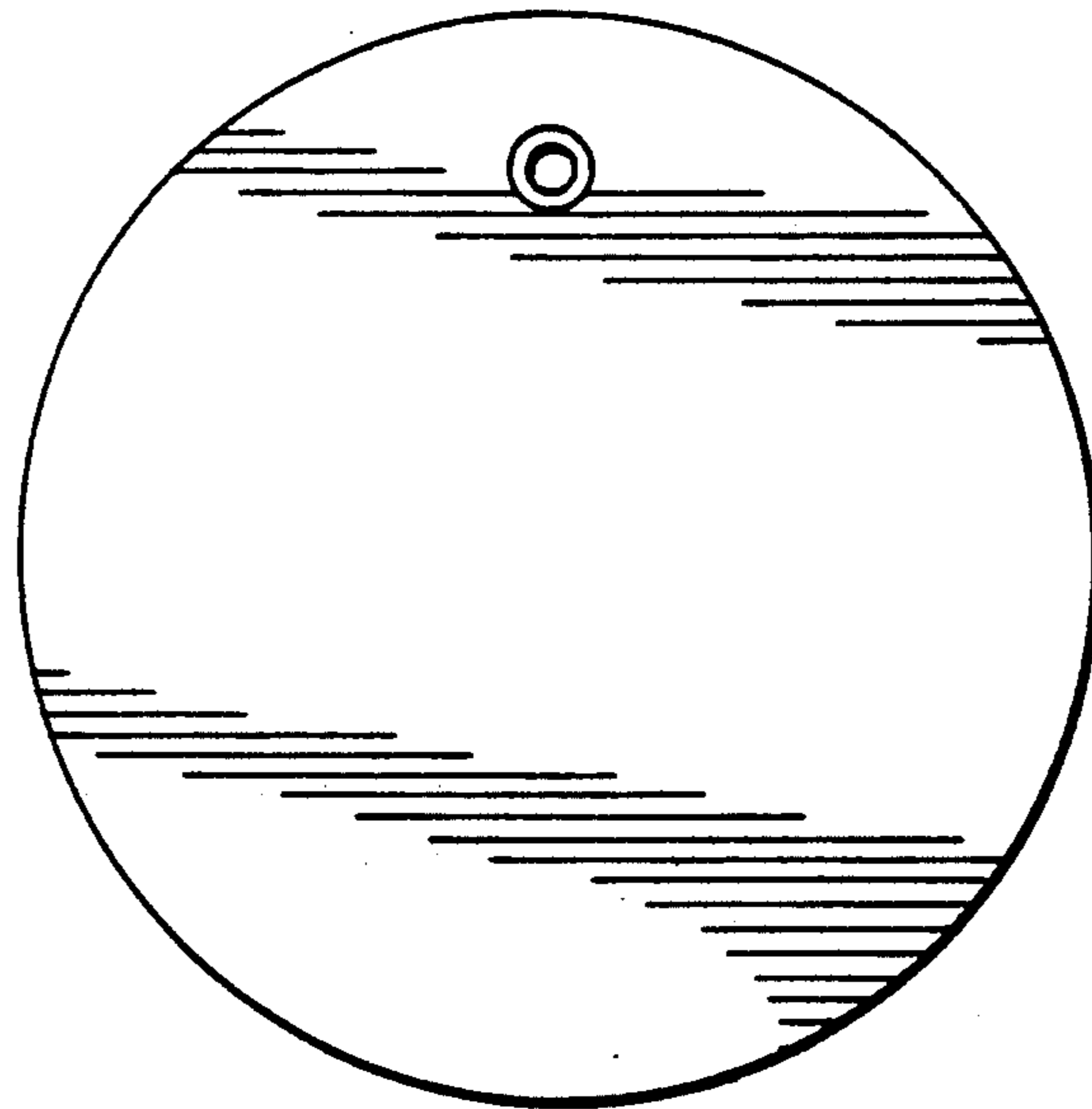


FIG. 4

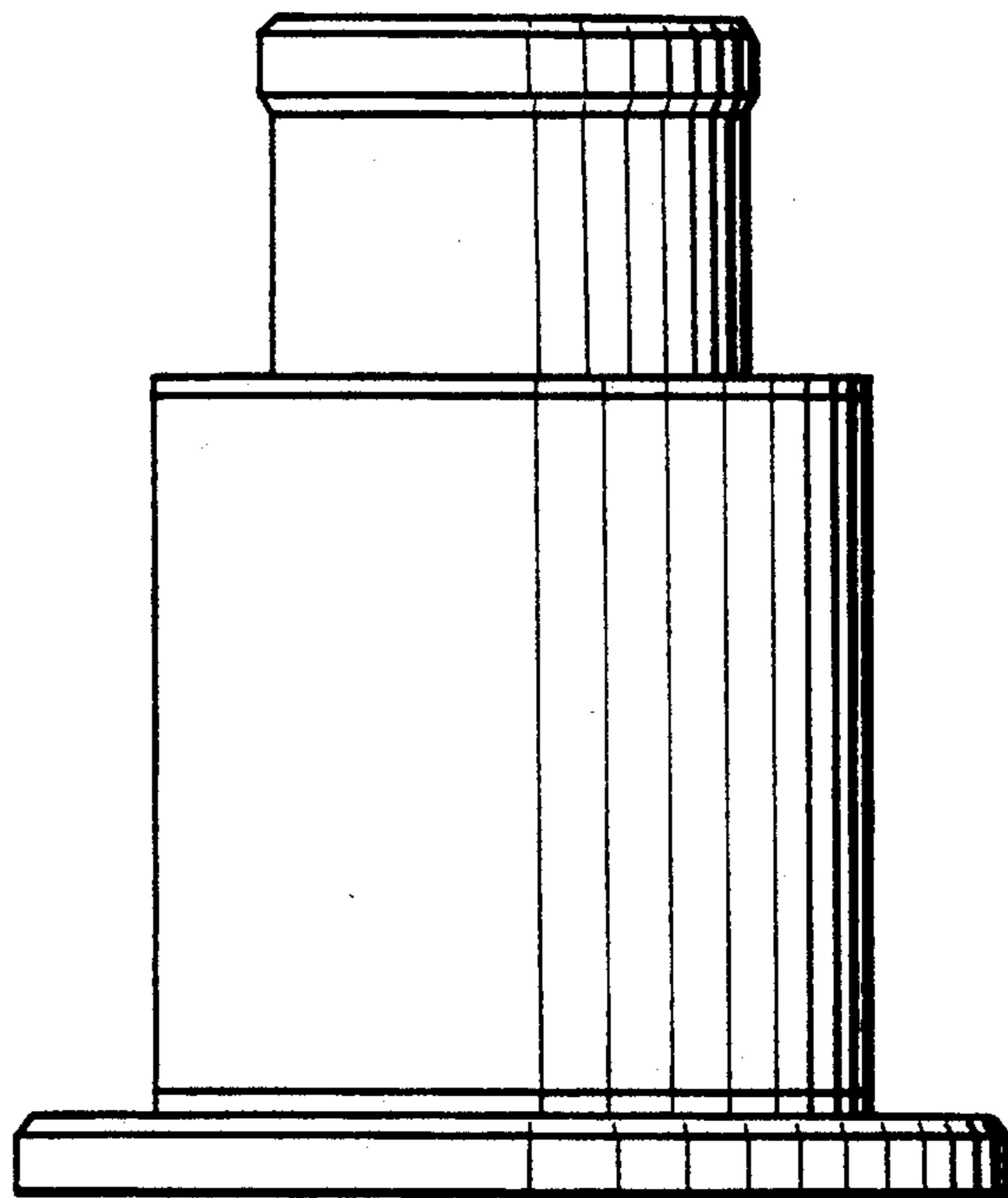


FIG. 5